



2214

Attorney's Docket No. 292-009001 / 2001E17454DE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Egon Mergenthaler et al.

Art Unit : 2814

Serial No. : 10/037,213

Examiner : Dana Farahani

Filed : November 9, 2001

Title : TIEDOWNS CONNECTED TO KERF REGIONS AND EDGE SEALS

Commissioner for Patents  
Washington, D.C. 20231

11/1/02  
Mergenthaler  
2/27/03

AMENDMENT

In response to the Office Action dated November 18, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 1, 7, 10 and 17 as follows:

--1. (Amended) A tiedown structure, comprising:

a semiconductor substrate having a chip formed thereon;

a kerf region proximate the chip; and

a conductive connector forming an electrical connection between the chip and the kerf region.

TECHNICAL  
11/1/02  
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2/27/03

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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Stefanie Dion